

样 品 承 认 书

Sample Approve Sheet

客户名称（Customer name）：

组件名称（Production name）： 方形 257 红灯

型 号（Model）： KGK-534RD-A1

编 号（Part number）：

日 期（Date）：

客户确认 Customer confirmation	审核 Checked by	编制 Prepared by

Device Selection Guide

ChipMaterials 芯片材料	Emitted Color 发光颜色	Resin Color 胶体颜色
AlGaInP	Brilliant Red	Red Diffused

Absolute Maximum Ratings (Ta=25℃)

(环境温度 Ambient temperature: 25℃)

项 目 Item	符号 Symbo	数值 Value	单位 Unit	备注 Remark
正向电流 Forward Current	IF	25	mA	---
正向峰值电流 Peck forward current	IFM	65	mA	F=1KHZ, 占空比(duty cycle)1/10
反向耐压 Reverse Voltage	VRP	5	V	---
耗散功率 Power Dissipation	Pd	60	mW	---
工作环境温度 Operation temperature	Tamb	-25 至 +80	℃	---
贮藏温度 Storage temperature	Tstg	-35 至 +85	℃	---
焊接温度 Soldering temperature	Tsol	260	℃	波峰焊,离环氧体 3mm 处≤3S Wave soldering, 3mm out of physical body, ≤3S

Electro-Optical Characteristics (Ta=25℃)

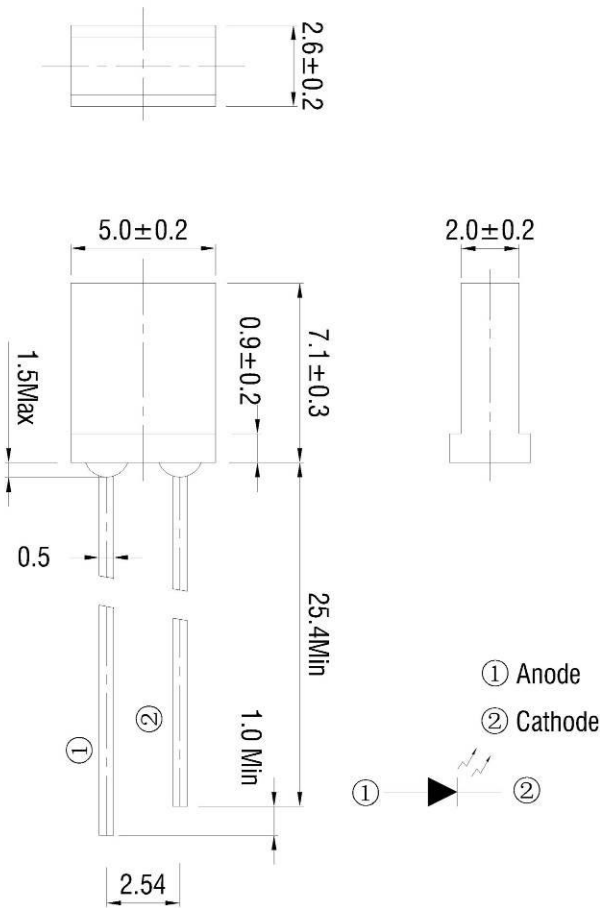
(环境温度 Ambient temperature: 25℃)

项目 Item	符号 Symbol	测试条件 Test condition	最小值 Min.	典型值 Type	最大值 Max..	单位 Unit.	备注
正向电压 Forward voltage	VF	IF=20mA	1.7	—	2.4	V	
反向电流 Reverse current	IR	VR=5V	—	—	10	μ A	
发光强度 Luminous intensity	IV	IF=20mA	60	90	—	mcd	
主波长 Dominant wavelength	λ d	IF=20mA	620	—	625	nm	
峰值波长 Peak wavelength	λ p	IF=20mA	—	632	—	nm	
视 角 Viewing Angle	2 θ 1/2	IF=20mA	—	125	—	deg	

实物图 Physical map: KGK-534-RD-A1

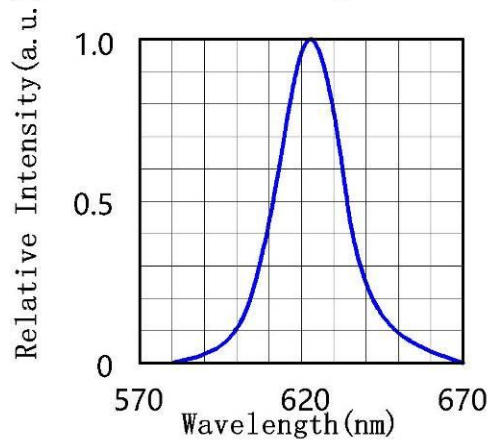


外形图 Outline dimensions: (单位: mm)

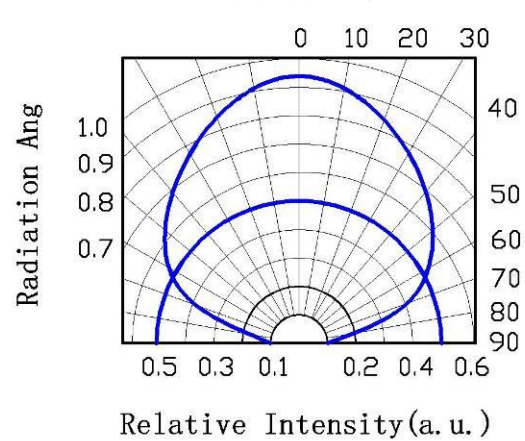


典型光电特性曲线图 Typical photoelectricity characteristic curve chart

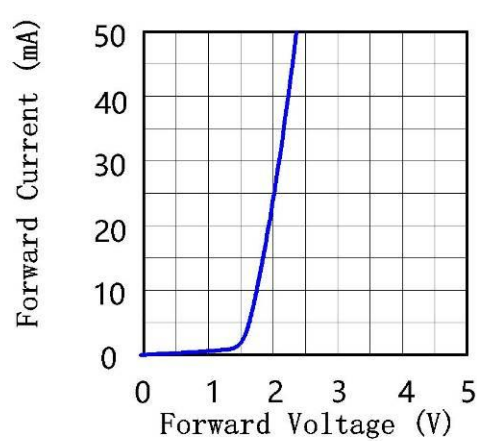
Relative Intensity vs. Wavelength



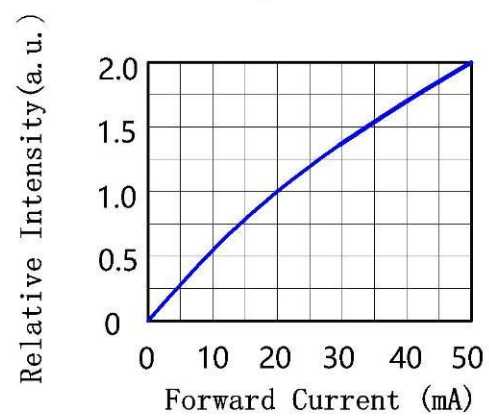
Directivity



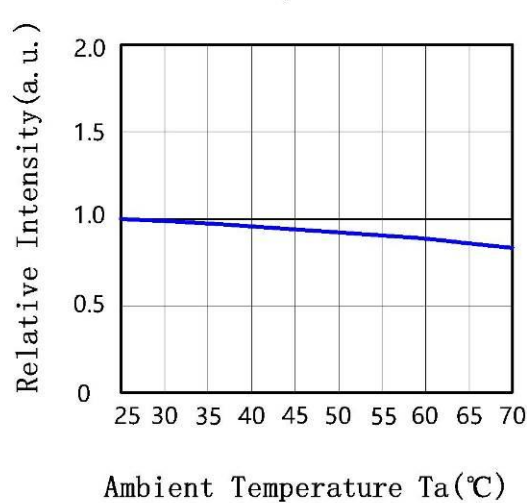
Forward Current vs. Forward Voltage



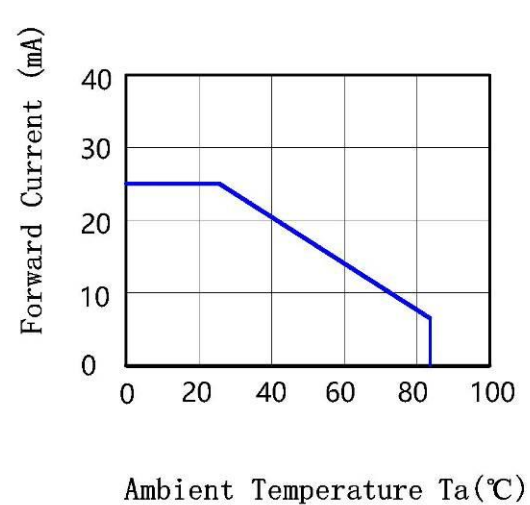
Relative Intensity vs. Forward Current



Relative Intensity vs. Ambient Temp.



Forward Current vs. Ambient Temp.



注意事项 Note

(一) 引脚成形方法 LED bracket forming method

(1) 必需离胶体 2 毫米才能折弯支架。

The pin of LED can be bent where is at least 2mm out of LED colloid.

(2) 支架成形必须用夹具或由专业人员来完成。

Must use fixture to deform the LED bracket.

(3) 支架成形必须在焊接前完成。

Finishing the forming of LED bracket must be before soldering.

(4) 支架成形需保证引脚和间距与线路板上一致。

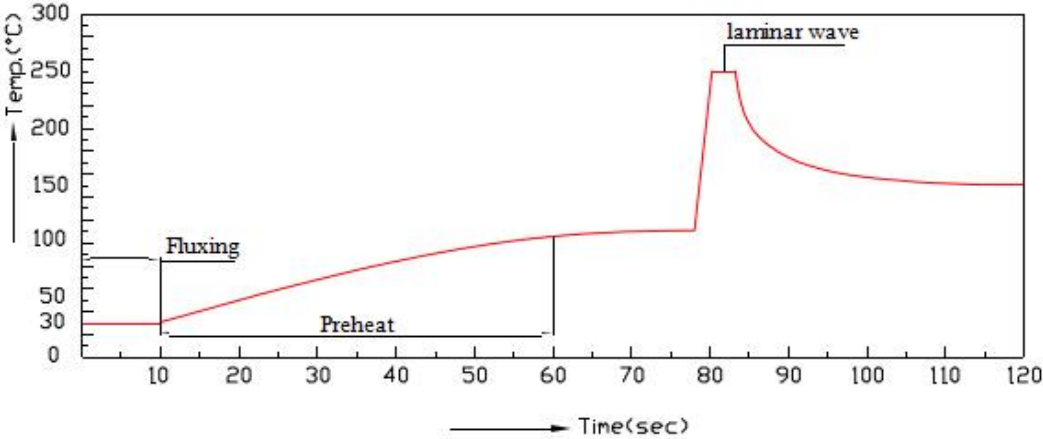
Guarantee the gap between two pin of LED tallys with LED pads in PCB when forming.

(二) 烙铁焊接 Manual soldering

烙铁（最高 30W）尖端温度不超过 300℃；焊接时间不超过 3 秒；焊接位置至少离胶体 3 毫米。

The tip temperature of soldering iron don't exceed 300℃；soldering time don't exceed 3s and soldering position must be 3mm out of led colloid.

Hand Soldering 手工焊接		DIP Soldering 浸焊	
Temp. at tip of iron 尖端温度	300℃ Max. (30W Max.)	Preheat temp. 预热温度	100℃ Max. (60 sec Max.)
Soldering time 焊接时间	3 sec Max.	Bath temp. & time 炉温&时间	260 Max., 5 sec Max
Distance 距离	3mm Min.(From solder joint to epoxy bulb)	Distance 距离	3mm Min. (From solder joint to epoxy bulb)



(三) 防静电措施 ESD countermeasure

静电及高压会对 LED 造成损坏，特别是芯片材质为 InGaN 的产品对静电防护要求更加严格，要求在使用和检验产品时戴防静电手腕带或防静电手套，焊接工具及设备外壳需可靠接地，焊接条件遵循此份规格书中的条件。

Static electricity and high volt can damage LED, The production whose Die material is InGaN must strictly required to prevent ESD, Must put on static glove and static fillet, Soldering tool and the cover of device must connect the

ground, soldering condition follows the related stating of production specification manual.

(四) 过电流保护 Protecting countermeasure when over current

为避免由于电压的变化引起大电流冲击而造成产品损坏，需要加入保护电阻。

Need add the protecting resistor in circuit in order to avoid damaging led due to big current and voltage fluctuation.

(五) LED 安装方法 LED installation method

1) 注意各类器件外线的排列以防极性装错，器件不可与发热组件靠得太近，工作条件不要超过其规定的极限。

Pay attention to the LED polarity and avoid installation wrong. LED can't be close to euthermic component, work condition should tally with it's specification.

2) 务必不要在引脚间距变形的情况下安装 LED。

Don't install the LED under the condition of the led pin deformation.

3) 当装配 LED 进入 PCB 或装配孔时，LED 支架不能承受任何压力。

The LED bracket don't load any pressure when installing the LED into PCB or fitting hole.

4) 在焊接温度回到正常以前，必须避免使 LED 受到任何的震动或外力。

Must avoid any strike and force on LED before the soldering temperature return to room temperature.

(六) 存储时间 Storage time

1) 在温度 $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$ ，湿度 RH60%条件下，产品可保存一年。超过保存期的产品需重新检测后方可使用。

LED can be stored for a year under the condition: the temperature of $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$ and humidity of RH60%, These production must be re-inspected and tested before use if their storage time exceed a year.

2) 如果打开的产品在 $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$ ，RH60%的空气条件下放置超过一周，则需要将产品在 $65^{\circ}\text{C} \pm 5^{\circ}\text{C}$ 的环境中放置 24 小时以上，并尽量在十五天内使用。

If LED is exposed in air for a week under the condition: the temperature of $5^{\circ}\text{C} \sim 35^{\circ}\text{C}$, humidity of RH60%, must place the LED in the ambience of $65^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 24 hours and use it in 15 days for best.

(七) 清洗 Cleaning

当用化学用品清洗胶体时必须特别小心，因为有些化学品对胶体表面有损伤并引起褪色如三氯乙烯、丙酮等。可用乙醇擦拭、浸渍，时间在常温下不超过 3 分钟。

Be careful of some chemical results in the LED colloid fades and damage when using chemical clean the LED, such as chloroethylene, acetone etc. Can use ethanol to wash or soak LED but the time don't exceed 3 minutes.

(八) 弯脚 (Kinked)

当 LED 成形弯脚时，弯脚模具容易刮花 LED 脚支架镀层，刮伤处容易生锈，特别是空气湿度大时。

为减少生锈机会，建议使用镀锡支架。

The kinked tooling scrape easily the pin of LED, where the LED bracket is rusting easily, especial expose it in moist air. To decrease the LED bracket rust, advise using plated tin LED bracket.